



# BYT79-600

Rectifier diode ultrafast

27 May 2015

Product data sheet

## 1. General description

Ultrafast, epitaxial rectifier diode in a SOD59 (TO-220AC) plastic package

## 2. Features and benefits

- Fast switching
- Low thermal resistance
- Soft recovery characteristic
- Low forward voltage drop
- Low switching loss
- High thermal cycling performance

## 3. Application information

- Output rectifiers in high frequency switched-mode power supplies
- Discontinuous Current Mode (DCM) Power Factor Correction (PFC)

## 4. Quick reference data

Table 1. Quick reference data

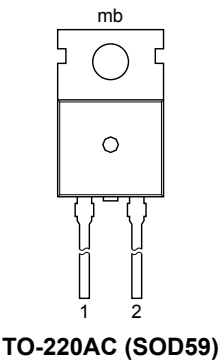
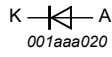
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{RRM}$	repetitive peak reverse voltage		-	-	600	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; $T_{mb} \leq 108$ °C; SQW; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a>	-	-	15	A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25$ $\mu$ s; $T_{mb} \leq 108$ °C; Square-wave	-	-	30	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10$ ms; $T_{j(init)} = 25$ °C; Sinusoidal waveform	-	-	130	A
		$t_p = 8.3$ ms; $T_{j(init)} = 25$ °C; Sinusoidal waveform	-	-	143	A
<b>Static characteristics</b>						
$V_F$	forward voltage	$I_F = 15$ A; $T_j = 150$ °C; <a href="#">Fig. 4</a>	-	1	1.2	V
		$I_F = 15$ A; $T_j = 25$ °C; <a href="#">Fig. 4</a>	-	1.17	1.38	V



Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Dynamic characteristics</b>						
$t_{rr}$	reverse recovery time	$I_F = 1\text{ A}$ ; $V_R \geq 30\text{ V}$ ; $dI_F/dt = 100\text{ A}/\mu\text{s}$ ; $T_J = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 5</a>	-	50	60	ns

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode	 <p>TO-220AC (SOD59)</p>	
2	A	anode		
mb	mb	mounting base; cathode		

## 6. Ordering information

Table 3. Ordering information

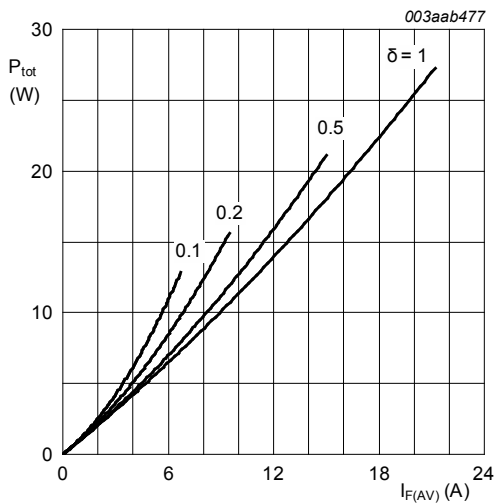
Type number	Package		
	Name	Description	Version
BYT79-600	TO-220AC	plastic single-ended package; heatsink mounted; 1 mounting hole; 2-lead TO-220AC	SOD59

## 7. Limiting values

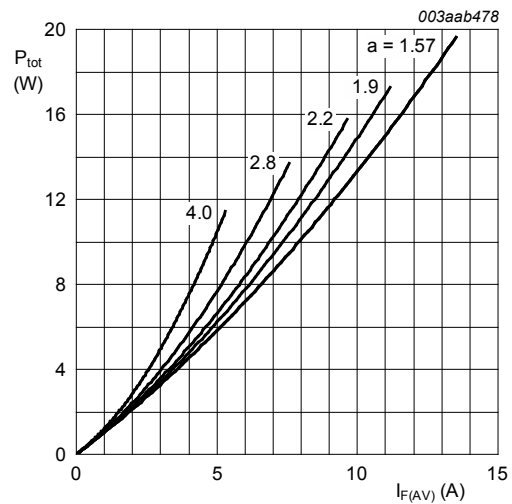
**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{RRM}$	repetitive peak reverse voltage		-	600	V
$V_{RWM}$	crest working reverse voltage		-	600	V
$V_R$	reverse voltage	Square-wave; $\delta = 1.0$	-	600	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; $T_{mb} \leq 108\text{ }^\circ\text{C}$ ; SQW; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a>	-	15	A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25\text{ }\mu\text{s}$ ; $T_{mb} \leq 108\text{ }^\circ\text{C}$ ; Square-wave	-	30	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; Sinusoidal waveform	-	130	A
		$t_p = 8.3\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; Sinusoidal waveform	-	143	A
$T_{stg}$	storage temperature		-55	150	$^\circ\text{C}$
$T_j$	junction temperature		-	150	$^\circ\text{C}$



**Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values**



**Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values**

## 8. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	with heatsink compound; <a href="#">Fig. 3</a>	-	-	2	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air		-	60	-	K/W

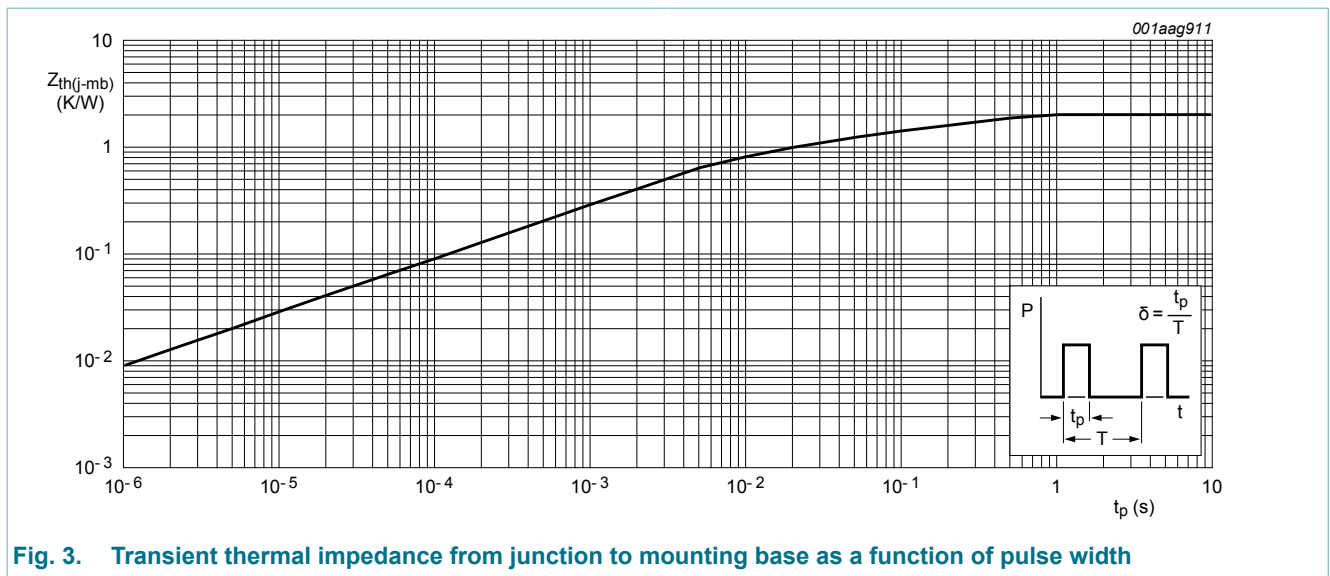
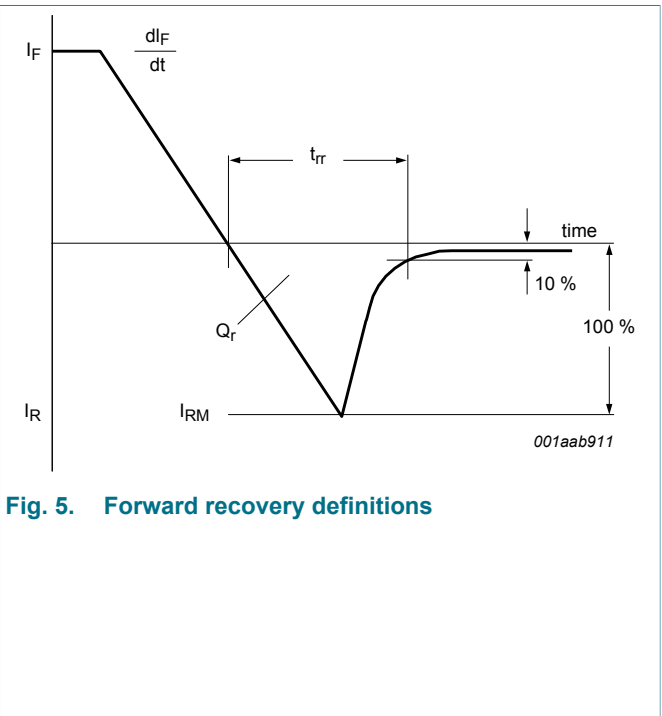
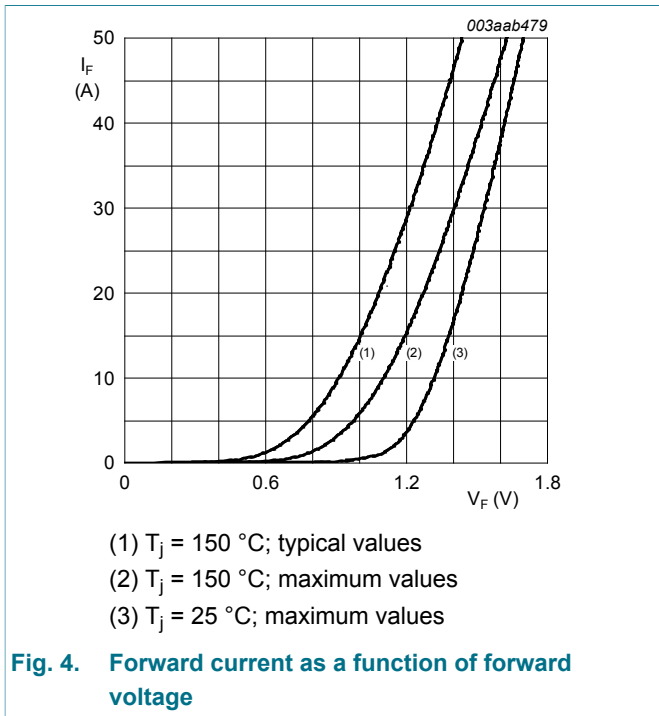


Fig. 3. Transient thermal impedance from junction to mounting base as a function of pulse width

### 9. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_F$	forward voltage	$I_F = 15 \text{ A}; T_j = 150 \text{ }^\circ\text{C}; \text{Fig. 4}$	-	1	1.2	V
		$I_F = 15 \text{ A}; T_j = 25 \text{ }^\circ\text{C}; \text{Fig. 4}$	-	1.17	1.38	V
$I_R$	reverse current	$V_R = 600 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	5	50	$\mu\text{A}$
		$V_R = 600 \text{ V}; T_j = 100 \text{ }^\circ\text{C}$	-	0.2	0.8	mA
<b>Dynamic characteristics</b>						
$Q_r$	recovered charge	$I_F = 2 \text{ A}; V_R \geq 30 \text{ V}; dI_F/dt = 20 \text{ A}/\mu\text{s}; \text{Fig. 5}$	-	40	70	nC
$t_{rr}$	reverse recovery time	$I_F = 1 \text{ A}; V_R \geq 30 \text{ V}; dI_F/dt = 100 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C}; \text{Fig. 5}$	-	50	60	ns
$I_{RM}$	peak reverse recovery current	$I_F = 10 \text{ A}; V_R \geq 30 \text{ V}; dI_F/dt = 50 \text{ A}/\mu\text{s}; T_j = 100 \text{ }^\circ\text{C}; \text{Fig. 5}$	-	3	5.2	A
$V_{FR}$	forward recovery voltage	$I_F = 10 \text{ A}; dI_F/dt = 10 \text{ A}/\mu\text{s}; \text{Fig. 6}$	-	3.2	-	V



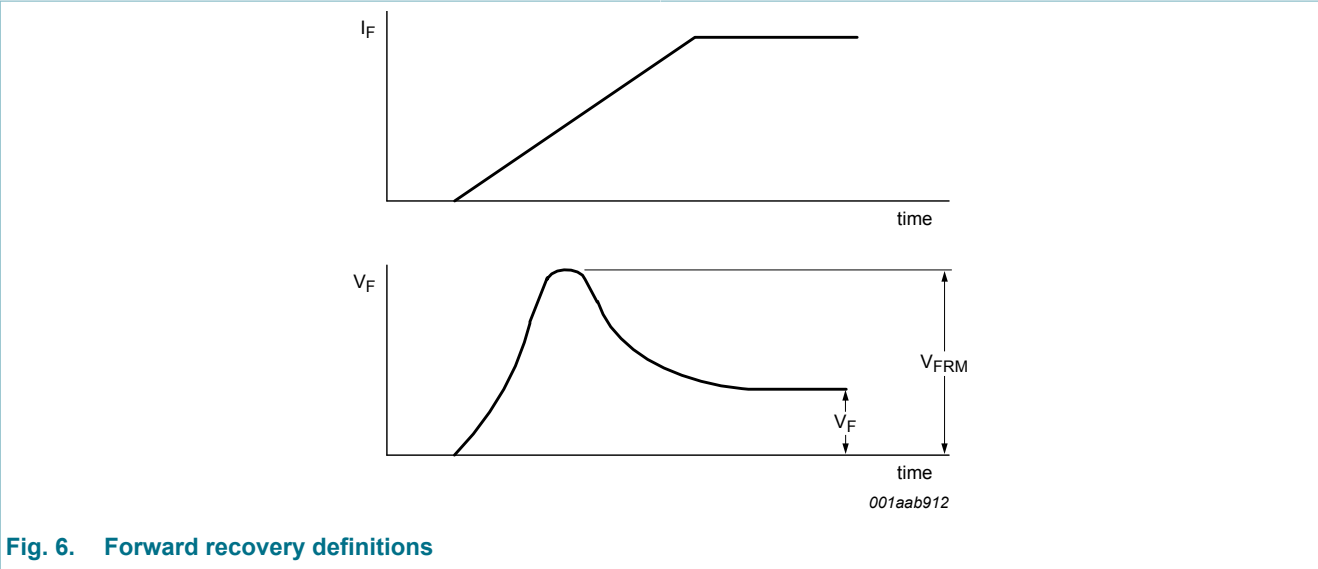
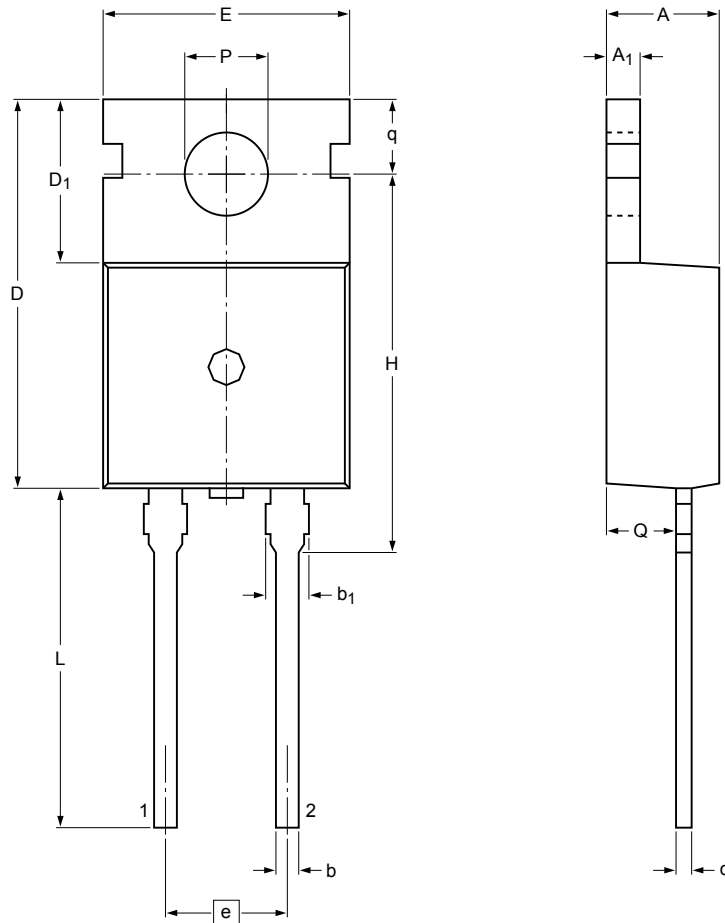


Fig. 6. Forward recovery definitions

### 10. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 2-lead TO-220AC SOD59



Dimensions

Unit	A	A <sub>1</sub>	b	b <sub>1</sub> <sup>(1)</sup>	c	D	D <sub>1</sub>	E	e	H	L	P	Q	q
max	4.7	1.40	0.95	1.7	0.65	15.8	6.8	10.30	5.08	16.25	15.0	3.80	2.6	2.9
nom									(REF)					
min	4.3	1.15	0.70	1.3	0.45	15.6	6.4	9.65		15.70	12.5	3.65	2.2	2.7

Note

1. Protruded dambar are included in the dimension.

sod059\_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOD59	2-lead TO-220AC				09-08-25 12-11-27

Fig. 7. Package outline TO-220AC (SOD59)

## 11. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Product [short] data sheet	Production	This document contains the product specification.

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